CPI0806J1R8R-10

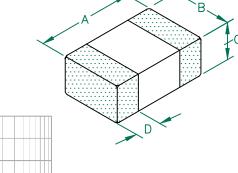
PHYSICAL DIMENSIONS:

4.0

A 2.00 [.079] ± 0.15[.006] B 1.60 [.063] ± 0.15[.006]

C 0.90 [.035] ± 0.10[.004]

D 0.50 [.020] ± 0.20[.008]



	ELECTRICAL CHARACTERISTICS:									
	L (μΗ) @ 1MHz ± 20%	DCR ($\frac{\Omega}{2}$) ± 30%	l (Max)							
Nom	1.80	0.20								
Min	1.44	0.14								
Max	2.16	0.26	1200mA							

NOTES: UNLESS OTHERWISE SPECIFIED

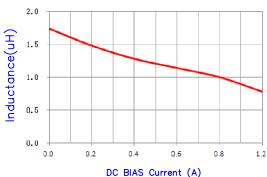
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

3.0 2.0 1.0 100 1,00

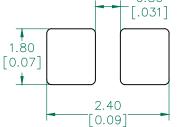
Ls vs Frequency

Frequency (MHz)

Ls vs DC BIAS Current

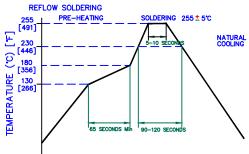


LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)







DIMENSIONS ARE IN mm [INCHES].					This print is the property of Laird Tech. and is loaned in confidence							
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I					with the understanding that no							
					copies shall be made without the written consent of Laird Tech. All	-						
I					rights to design or invention are	_						
I					reserved.	REV						
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Ī	В	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11 SCA		E NTS S		-			
ı	Α	ORIGINAL DRAFT	03/01/11	QU	, ,	00L #	1413	١.				
1	REV	DESCRIPTION	DATE	INT	CPI0806J1R8R-10-B		_	1	of 1			